Hex Schmitt-Trigger Inverter

High-Performance Silicon-Gate CMOS

The 74HC14 is identical in pinout to the LS14, LS04 and the HC04. The device inputs are compatible with Standard CMOS outputs; with pullup resistors, they are compatible with LSTTL outputs.

The HC14 is useful to "square up" slow input rise and fall times. Due to hysteresis voltage of the Schmitt trigger, the HC14 finds applications in noisy environments.

Features

- Output Drive Capability: 10 LSTTL Loads
- Outputs Directly Interface to CMOS, NMOS and TTL
- Operating Voltage Range: 2.0 to 6.0 V
- Low Input Current: 1.0 μA
- High Noise Immunity Characteristic of CMOS Devices
- In Compliance With the JEDEC Standard No. 7A Requirements
- ESD Performance: HBM > 2000 V; Machine Model > 200 V
- Chip Complexity: 60 FETs or 15 Equivalent Gates
- These are Pb-Free Devices



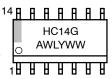
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MARKING DIAGRAMS



SOIC-14 D SUFFIX CASE 751A





TSSOP-14 DT SUFFIX CASE 948G



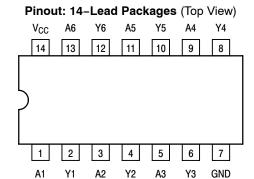
HC14 = Device Code A = Assembly Location

L, WL = Wafer Lot Y = Year W, WW = Work Week G or • = Pb-Free Package

(Note: Microdot may be in either location)

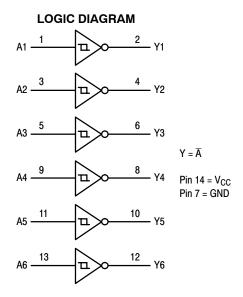
ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.



FUNCTION TABLE

| Inputs | Outputs |
|--------|---------|
| Α | Y |
| L | Н |
| Н | L |



ORDERING INFORMATION

| Device | Package | Shipping [†] |
|-------------|----------------------|-----------------------|
| 74HC14DR2G | SOIC-14 (Pb-Free) | 2500 / Tape & Reel |
| 74HC14DTR2G | TSSOP-14* | 2500 / Tape & Reel |

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.
*This package is inherently Pb-Free.

MAXIMUM RATINGS

| Symbol | Parameter | Value | Unit |
|------------------|--|--------------------------------|------|
| V _{CC} | DC Supply Voltage (Referenced to GND) | - 0.5 to + 7.0 | V |
| V _{in} | DC Input Voltage (Referenced to GND) | - 0.5 to V _{CC} + 0.5 | V |
| V _{out} | DC Output Voltage (Referenced to GND) | - 0.5 to V _{CC} + 0.5 | V |
| I _{in} | DC Input Current, per Pin | ±20 | mA |
| I _{out} | DC Output Current, per Pin | ±25 | mA |
| I _{CC} | DC Supply Current, V _{CC} and GND Pins | ±50 | mA |
| P _D | Power Dissipation in Still Air, SOIC Package† TSSOP Package† | 500 450 | mW |
| T _{stg} | Storage Temperature Range | - 65 to + 150 | °C |
| TL | Lead Temperature, 1 mm from Case for 10 Seconds SOIC or TSSOP Package | 260 | °C |

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high–impedance circuit. For proper operation, V_{in} and V_{out} should be constrained to the range GND \leq (V_{in} or V_{out}) \leq V_{CC} .

Unused inputs must always be tied to an appropriate logic voltage level (e.g., either GND or V_{CC}). Unused outputs must be left open.

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

TSSOP Package: - 6.1 mW/°C from 65° to 125°C

For high frequency or heavy load considerations, see Chapter 2 of the ON Semiconductor High-Speed CMOS Data Book (DL129/D).

RECOMMENDED OPERATING CONDITIONS

| Symbol | Parameter | Min | Max | Unit |
|------------------------------------|--|-------------|-------------------------------------|------|
| V _{CC} | DC Supply Voltage (Referenced to GND) | 2.0 | 6.0 | V |
| V _{in} , V _{out} | DC Input Voltage, Output Voltage (Referenced to GND) | 0 | V _{CC} | V |
| T _A | Operating Temperature Range, All Package Types | - 55 | + 125 | °C |
| t _r , t _f | Input Rise/Fall Time $V_{CC} = 2.0 \text{ V}$ (Figure 1) $V_{CC} = 4.5 \text{ V}$ $V_{CC} = 6.0 \text{ V}$ | 0 0 0 | No Limit* No Limit* No Limit* | ns |

^{*}When $V_{in} = 50\% V_{CC}$, $I_{CC} > 1mA$

[†]Derating — SOIC Package: - 7 mW/°C from 65° to 125°C

DC CHARACTERISTICS (Voltages Referenced to GND)

| | | | | Voc | V _{CC} Guaranteed Limit | | | |
|------------------------------|---|--|---|--------------------------|----------------------------------|------------------------------|------------------------------|------|
| Symbol | Parameter | Conditi | on | (V) | -55 to 25°C | ≤ 85°C | ≤125°C | Unit |
| V _{T+} max | Maximum Positive-Going Input Threshold Voltage (Figure 3) | $V_{out} = 0.1V$ $ I_{out} \le 20\mu A$ | | 2.0 3.0 4.5 6.0 | 1.50 2.15 3.15 4.20 | 1.50 2.15 3.15 4.20 | 1.50 2.15 3.15 4.20 | V |
| V _{T+} min | Minimum Positive-Going Input Threshold Voltage (Figure 3) | $V_{out} = 0.1V$ $ I_{out} \le 20\mu A$ | | 2.0 3.0 4.5 6.0 | 1.0 1.5 2.3 3.0 | 0.95 1.45 2.25 2.95 | 0.95 1.45 2.25 2.95 | V |
| V _{T-} max | Maximum Negative-Going Input Threshold Voltage (Figure 3) | $\begin{aligned} V_{out} &= V_{CC} - 0.1V \\ I_{out} &\leq 20 \mu A \end{aligned}$ | | 2.0 3.0 4.5 6.0 | 0.9 1.4 2.0 2.6 | 0.95 1.45 2.05 2.65 | 0.95 1.45 2.05 2.65 | V |
| V _T min | Minimum Negative-Going Input Threshold Voltage (Figure 3) | $V_{out} = V_{CC} - 0.1V$ $ I_{out} \le 20\mu A$ | | 2.0 3.0 4.5 6.0 | 0.3 0.5 0.9 1.2 | 0.3 0.5 0.9 1.2 | 0.3 0.5 0.9 1.2 | V |
| V _H max Note 2 | Maximum Hysteresis Voltage (Figure 3) | $V_{out} = 0.1V \text{ or } V_{CC}$ $ I_{out} \le 20\mu\text{A}$ | . – 0.1V | 2.0 3.0 4.5 6.0 | 1.20 1.65 2.25 3.00 | 1.20 1.65 2.25 3.00 | 1.20 1.65 2.25 3.00 | V |
| V _H min Note 2 | Minimum Hysteresis Voltage (Figure 3) | $V_{out} = 0.1V \text{ or } V_{CC}$ $ I_{out} \le 20 \mu A$ | , – 0.1V | 2.0 3.0 4.5 6.0 | 0.20 0.25 0.40 0.50 | 0.20 0.25 0.40 0.50 | 0.20 0.25 0.40 0.50 | V |
| V _{OH} | Minimum High-Level Output Voltage | $V_{in} \le V_{T-} min$ $ I_{out} \le 20\mu A$ | | 2.0 4.5 6.0 | 1.9 4.4 5.9 | 1.9 4.4 5.9 | 1.9 4.4 5.9 | V |
| | | V _{in} ≤ V _{T−} min | $ I_{out} \le 2.4 \text{mA}$ $ I_{out} \le 4.0 \text{mA}$ $ I_{out} \le 5.2 \text{mA}$ | 3.0 4.5 6.0 | 2.48 3.98 5.48 | 2.34 3.84 5.34 | 2.20 3.70 5.20 | |
| V _{OL} | Maximum Low-Level Output Voltage | $V_{in} \ge V_{T+} \max$ $ I_{out} \le 20\mu A$ | | 2.0 4.5 6.0 | 0.1 0.1 0.1 | 0.1 0.1 0.1 | 0.1 0.1 0.1 | ٧ |
| | | V _{in} ≥ V _{T+} max | $ I_{out} \le 2.4 \text{mA}$ $ I_{out} \le 4.0 \text{mA}$ $ I_{out} \le 5.2 \text{mA}$ | 3.0 4.5 6.0 | 0.26 0.26 0.26 | 0.33 0.33 0.33 | 0.40 0.40 0.40 | |
| I _{in} | Maximum Input Leakage Current | $V_{in} = V_{CC}$ or GND | | 6.0 | ±0.1 | ±1.0 | ±1.0 | μΑ |
| Icc | Maximum Quiescent Supply Current (per Package) | $V_{in} = V_{CC}$ or GND $I_{out} = 0\mu A$ | | 6.0 | 2.0 | 20 | 40 | μΑ |

Information on typical parametric values along with frequency or heavy load considerations can be found in Chapter 2 of the ON Semiconductor High-Speed CMOS Data Book (DL129/D).
 V_Hmin > (V_{T+} min) - (V_{T-} max); V_Hmax = (V_{T+} max) - (V_{T-} min).

$\textbf{AC CHARACTERISTICS } (C_L = 50 \text{pF, Input } t_r = t_f = 6 \text{ns})$

| | | Voc | V _{CC} Guaranteed Limit | | | |
|--|---|--------------------------|----------------------------------|----------------------|-----------------------|------|
| Symbol | Parameter | (V) | -55 to 25°C | ≤85°C | ≤125°C | Unit |
| t _{PLH} , t _{PHL} | Maximum Propagation Delay, Input A or B to Output Y (Figures 1 and 2) | 2.0 3.0 4.5 6.0 | 75 30 15 13 | 95 40 19 16 | 110 55 22 19 | ns |
| t _{TLH} , t _{THL} | Maximum Output Transition Time, Any Output (Figures 1 and 2) | 2.0 3.0 4.5 6.0 | 75 27 15 13 | 95 32 19 16 | 110 36 22 19 | ns |
| C _{in} | Maximum Input Capacitance | | 10 | 10 | 10 | pF |

NOTE: For propagation delays with loads other than 50 pF, and information on typical parametric values, see Chapter 2 of the ON Semiconductor High-Speed CMOS Data Book (DL129/D).

| | | Typical @ 25°C, V _{CC} = 5.0 V | |
|----------|---|---|----|
| C_{PD} | Power Dissipation Capacitance (Per Inverter)* | 22 | pF |

^{*}Used to determine the no–load dynamic power consumption: P_D = C_{PD} V_{CC}²f + I_{CC} V_{CC}. For load considerations, see Chapter 2 of the ON Semiconductor High–Speed CMOS Data Book (DL129/D).

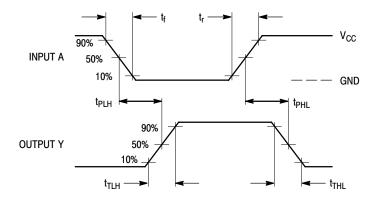
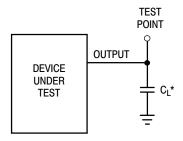


Figure 1. Switching Waveforms



*Includes all probe and jig capacitance

Figure 2. Test Circuit

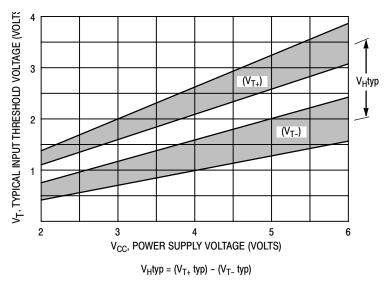
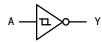
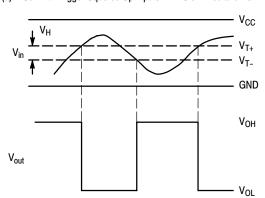


Figure 3. Typical Input Threshold, V_{T_+}, V_{T_-} versus Power Supply Voltage



(a) A Schmitt-Trigger Squares Up Inputs With Slow Rise and Fall Times



(b) A Schmitt-Trigger Offers Maximum Noise Immunity

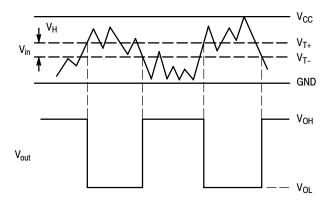
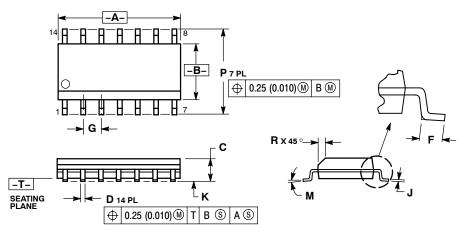


Figure 4. Typical Schmitt-Trigger Applications

PACKAGE DIMENSIONS

SOIC-14 CASE 751A-03 **ISSUE H**



- NOTES:

 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

 2. CONTROLLING DIMENSION: MILLIMETER.

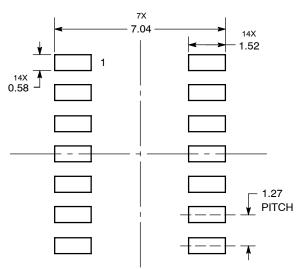
 3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.

 4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.

 5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

| | MILLIN | IETERS | INC | HES |
|-----|--------|---------|-------|-------|
| DIM | MIN | MIN MAX | | MAX |
| Α | 8.55 | 8.75 | 0.337 | 0.344 |
| В | 3.80 | 4.00 | 0.150 | 0.157 |
| С | 1.35 | 1.75 | 0.054 | 0.068 |
| D | 0.35 | 0.49 | 0.014 | 0.019 |
| F | 0.40 | 1.25 | 0.016 | 0.049 |
| G | 1.27 | BSC | 0.050 | BSC |
| J | 0.19 | 0.25 | 0.008 | 0.009 |
| K | 0.10 | 0.25 | 0.004 | 0.009 |
| М | 0 ° | 7 ° | 0 ° | 7 ° |
| Р | 5.80 | 6.20 | 0.228 | 0.244 |
| B | 0.25 | 0.50 | 0.010 | 0.010 |

SOLDERING FOOTPRINT*

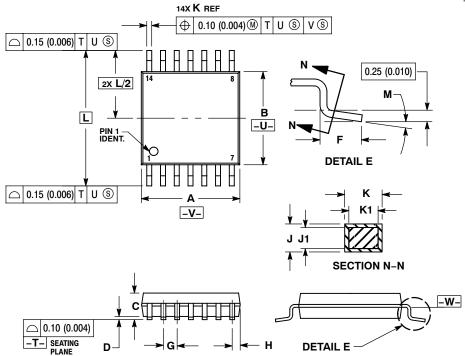


DIMENSIONS: MILLIMETERS

^{*}For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

TSSOP-14 CASE 948G-01 **ISSUE B**



- NOTES:
 1. DIMENSIONING AND TOLERANCING PER
 - 1. DIMENSION R DOES NOT INCLUDE

 1. CONTROLLING DIMENSION: MILLIMETER.
 2. CONTROLLING DIMENSION: MILLIMETER.
 3. DIMENSION A DOES NOT INCLUDE MOLD
 FLASH, PROTRUSIONS OR GATE BURRS.
 MOLD FLASH OR GATE BURRS SHALL NOT
 EXCEED 0.15 (0.006) PER SIDE.

 2. DIMENSION R DOES NOT INCLUDE

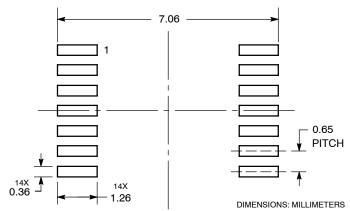
 1. DIMENSION R DO
 - 4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION.
 - INTERLEAD FLASH OR PROTRUSION.
 INTERLEAD FLASH OR PROTRUSION SHALL
 NOT EXCEED 0.25 (0.010) PER SIDE.
 5. DIMENSION K DOES NOT INCLUDE
 DAMBAR PROTRUSION. ALLOWABLE
 DAMBAR PROTRUSION SHALL BE 0.08
 (0.003) TOTAL IN EXCESS OF THE K
 DIMENSION AT MAXIMUM MATERIAL
 CONDITION.
 6. TERMINAL NUMBERS ARE SHOWN FOR
 REFERENCE ONLY

 - REFERENCE ONLY.

 7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

| | MILLIN | IETERS | INC | HES | |
|-----|--------|--------|-----------|-------|--|
| DIM | MIN | MAX | MIN | MAX | |
| Α | 4.90 | 5.10 | 0.193 | 0.200 | |
| В | 4.30 | 4.50 | 0.169 | 0.177 | |
| С | | 1.20 | | 0.047 | |
| D | 0.05 | 0.15 | 0.002 | 0.006 | |
| F | 0.50 | 0.75 | 0.020 | 0.030 | |
| G | 0.65 | BSC | 0.026 | BSC | |
| Н | 0.50 | 0.60 | 0.020 | 0.024 | |
| J | 0.09 | 0.20 | 0.004 | 0.008 | |
| J1 | 0.09 | 0.16 | 0.004 | 0.006 | |
| K | 0.19 | 0.30 | 0.007 | 0.012 | |
| K1 | 0.19 | 0.25 | 0.007 | 0.010 | |
| L | 6.40 | BSC | 0.252 BSC | | |
| М | 0 ° | 8 ° | 0 ° | 8 ° | |

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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74HC14/D